

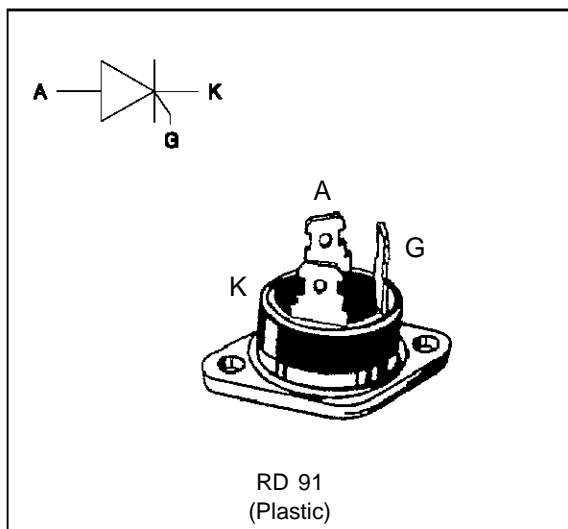
FEATURES

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY
- ISOLATED PACKAGE :
INSULATED VOLTAGE = 2500V_(RMS)
(UL RECOGNIZED : E81734)

DESCRIPTION

The BTW 66 and BTW 67 Family Silicon Controlled Rectifiers are high performance glass passivated chips technology.

This general purpose Family Silicon Controlled Rectifiers is designed for power supply up to 400Hz on resistive or inductive load.



ABSOLUTE RATINGS (limiting values)

| Symbol | Parameter | Value | Unit |
|------------------------------------|---|------------------------------------|--------------------------------|
| I _{T(RMS)} | RMS on-state current (180° conduction angle) | BTW 66 T _c =75°C | 30 |
| | | BTW 67 T _c =75°C | 40 |
| I _{T(AV)} | Average on-state current (180° conduction angle, single phase circuit) | BTW 66 T _c =75°C | 20 |
| | | BTW 67 T _c =75°C | 25 |
| I _{TSM} | Non repetitive surge peak on-state current (T _j initial = 25°C) | BTW 66 tp=8.3 ms | 420 |
| | | BTW 67 tp=8.3 ms | 525 |
| | | BTW 66 tp=10 ms | 400 |
| | | BTW 67 tp=10 ms | 500 |
| I ² t | I ² t value | BTW 66 tp=10 ms BTW 67 tp=10 ms | 800 1250 |
| di/dt | Critical rate of rise of on-state current Gate supply : I _G = 100 mA di _G /dt = 1 A/μs | | 100 |
| T _{stg} T _j | Storage and operating junction temperature range | | - 40 to + 150 - 40 to + 125 |
| TI | Maximum lead temperature for soldering during 10 s at 4.5 mm from case | | 230 |

| Symbol | Parameter | BTW 66- / BTW 67- | | | | | | Unit |
|--------------------------------------|--|-------------------|-----|-----|-----|------|------|------|
| | | 200 | 400 | 600 | 800 | 1000 | 1200 | |
| V _{DRM} V _{RRM} | Repetitive peak off-state voltage T _j = 125 °C | 200 | 400 | 600 | 800 | 1000 | 1200 | V |

THERMAL RESISTANCES

| Symbol | Parameter | | Value | Unit | |
|--------------|----------------------------|--|--------|------|------|
| Rth (c-h) | Contact (case to heatsink) | | 0.10 | °C/W | |
| Rth (j-c) DC | Junction to case for DC | | BTW 66 | 1.2 | °C/W |
| | | | BTW 67 | 1.0 | |

GATE CHARACTERISTICS (maximum values)

 $P_G (AV) = 1W$ $P_{GM} = 40W$ (tp = 20 μs) $I_{FGM} = 8A$ (tp = 20 μs) $V_{RGM} = 5V$.

ELECTRICAL CHARACTERISTICS

| Symbol | Test Conditions | | | Value | | Unit |
|--------------------------------------|--|---|------------------------|--------|------------|------------|
| | | | | BTW 66 | BTW 67 | |
| I _{GT} | V _D =12V (DC) R _L =33 Ω | T _j =25°C | MAX | 50 | 80 | mA |
| V _{GT} | V _D =12V (DC) R _L =33 Ω | T _j =25°C | MAX | 1.5 | | V |
| V _{GD} | V _D =V _{DRM} R _L =3.3k Ω | T _j = 125°C | MIN | 0.2 | | V |
| t _{gt} | V _D =V _{DRM} I _G = 200mA dI _G /dt = 1.5A/ μs | T _j =25°C | TYP | 2 | | μs |
| I _L | I _G = 1.2 I _{GT} | T _j =25°C | TYP | 50 | | mA |
| I _H | I _T = 500mA gate open | T _j =25°C | MAX | 75 | 150 | mA |
| V _{TM} | BTW 66 I _{TM} = 60A BTW 67 I _{TM} = 80A tp= 380 μs | T _j =25°C | MAX | 2.2 | 2.0 | V |
| I _{DRM} I _{RRM} | V _{DRM} Rated V _{RRM} Rated | T _j =25°C | MAX | 0.02 | | mA |
| | | T _j = 125°C | | 6 | | |
| dV/dt | Linear slope up to V _D =67%V _{DRM} gate open | V _{DRM} ≤ 800V V _{DRM} ≥ 1000V | T _j = 125°C | MIN | 500 250 | V/ μs |
| t _q | V _D =67%V _{DRM} dI _{TM} /dt=30 A/ μs | I _{TM} = 60A V _R = 75V dV _D /dt= 20V/ μs | T _j = 125°C | TYP | 100 | μs |

| Package | $I_{T(RMS)}$ | V_{DRM} / V_{RRM} | Sensitivity Specification |
|-----------------------|--------------|---------------------|---------------------------|
| | A | V | BTW |
| BTW 66 (Insulated) | 30 | 200 | X |
| | | 400 | X |
| | | 600 | X |
| | | 800 | X |
| | | 1000 | X |
| | | 1200 | X |
| BTW 67 (Insulated) | 40 | 200 | X |
| | | 400 | X |
| | | 600 | X |
| | | 800 | X |
| | | 1000 | X |
| | | 1200 | X |

Fig.1 : Maximum average power dissipation versus average on-state current (BTW 66).

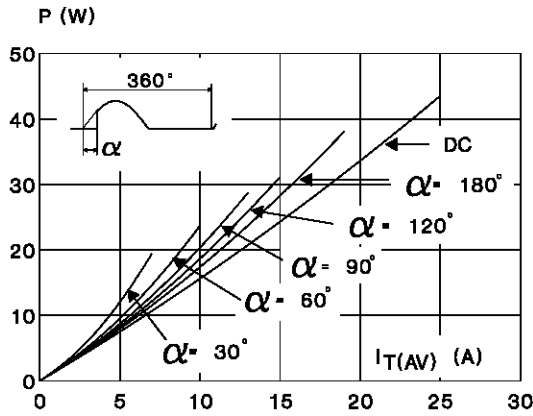


Fig.3 : Maximum average power dissipation versus average on-state current (BTW 67).

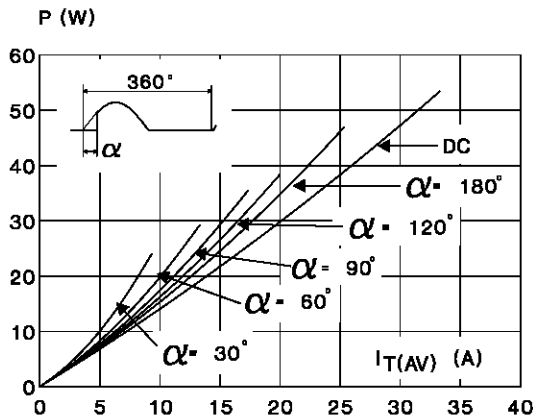


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTW 66).

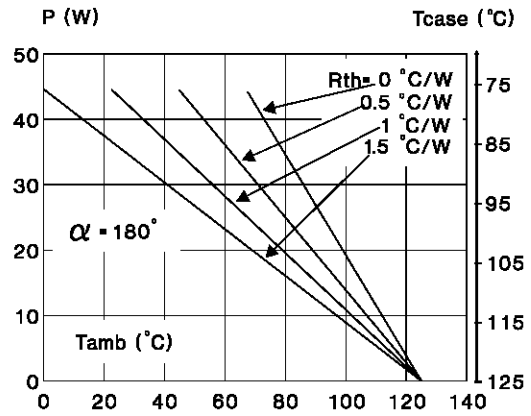


Fig.4 : Correlation between maximum average power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact (BTW 67).

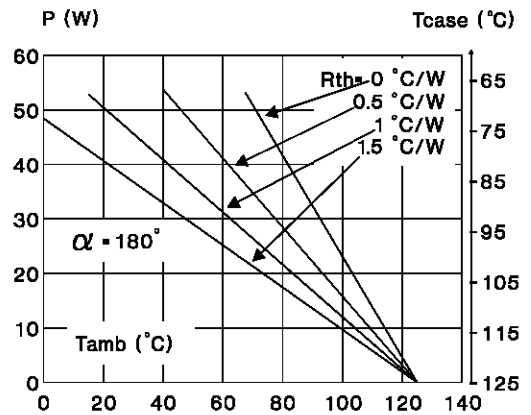


Fig.5 : Average on-state current versus case temperature (BTW 66).

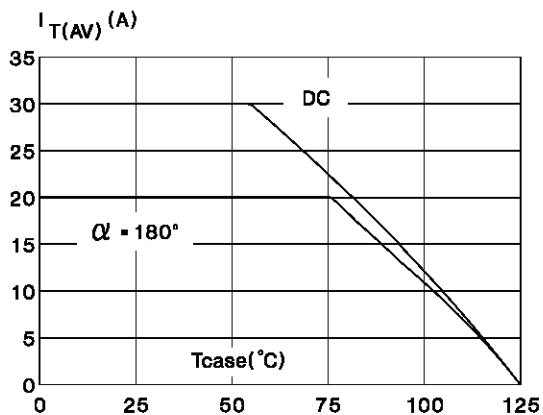


Fig.6 : Average on-state current versus case temperature (BTW 67).

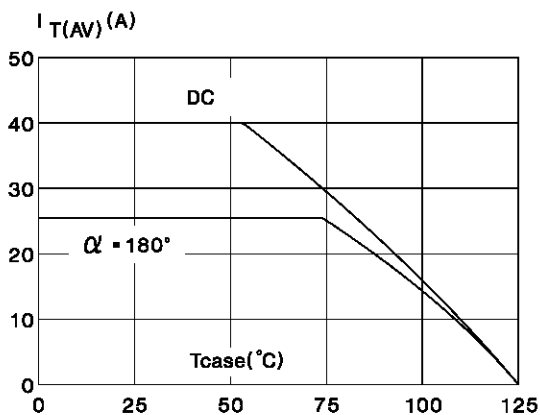


Fig.7 : Relative variation of thermal impedance junction to case versus pulse duration.

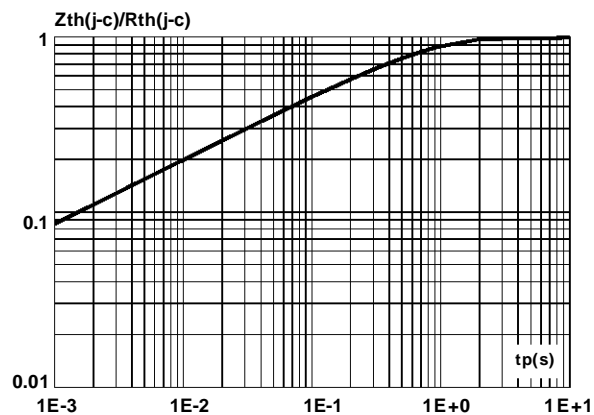


Fig.8 : Relative variation of gate trigger current versus junction temperature.

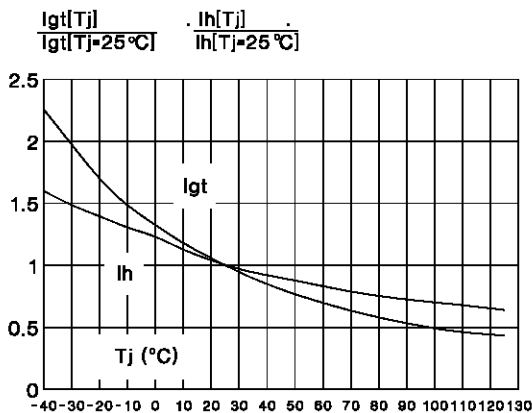


Fig.9 : Non repetitive surge peak on-state current versus number of cycles (BTW 66).

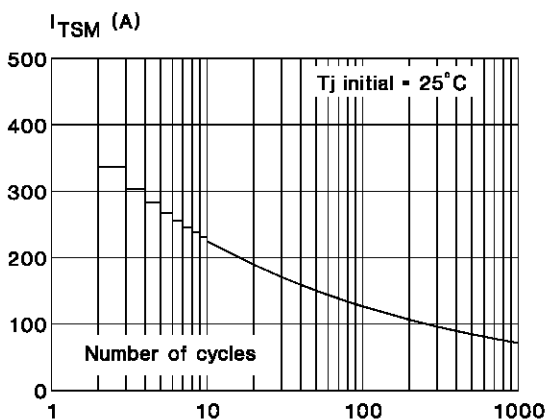


Fig.10 : Non repetitive surge peak on-state current versus number of cycles (BTW 67).

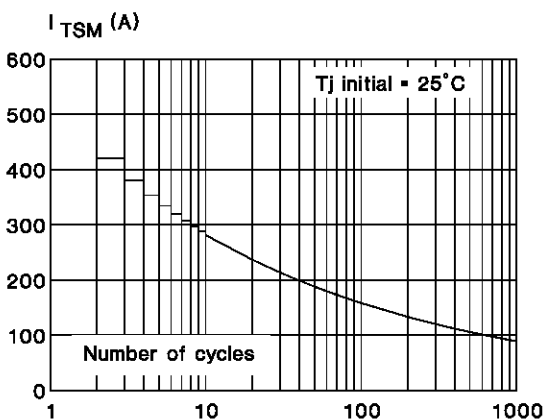


Fig.11 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t (BTW 66).

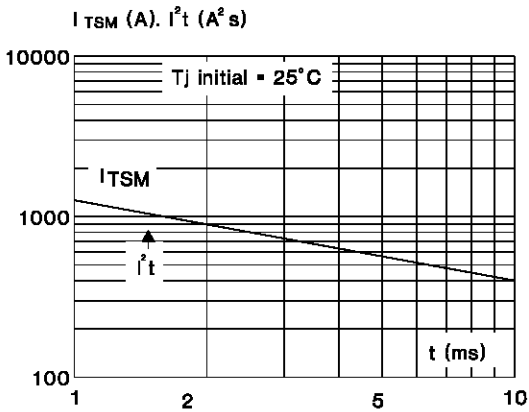


Fig.12 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t (BTW 67).

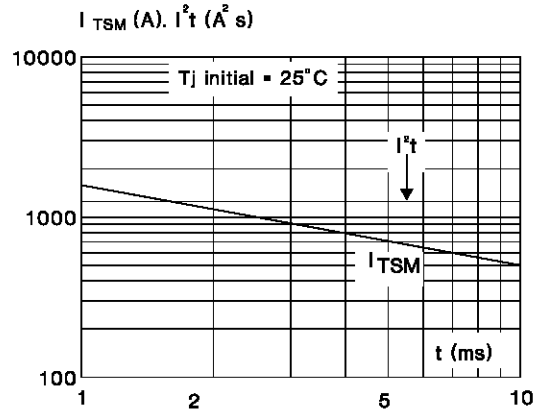


Fig.13 : On-state characteristics (maximum values) (BTW 66).

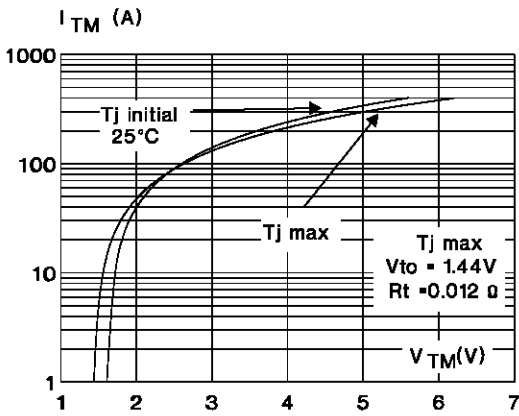
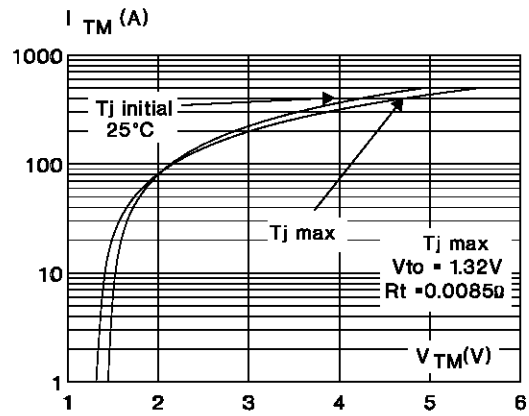
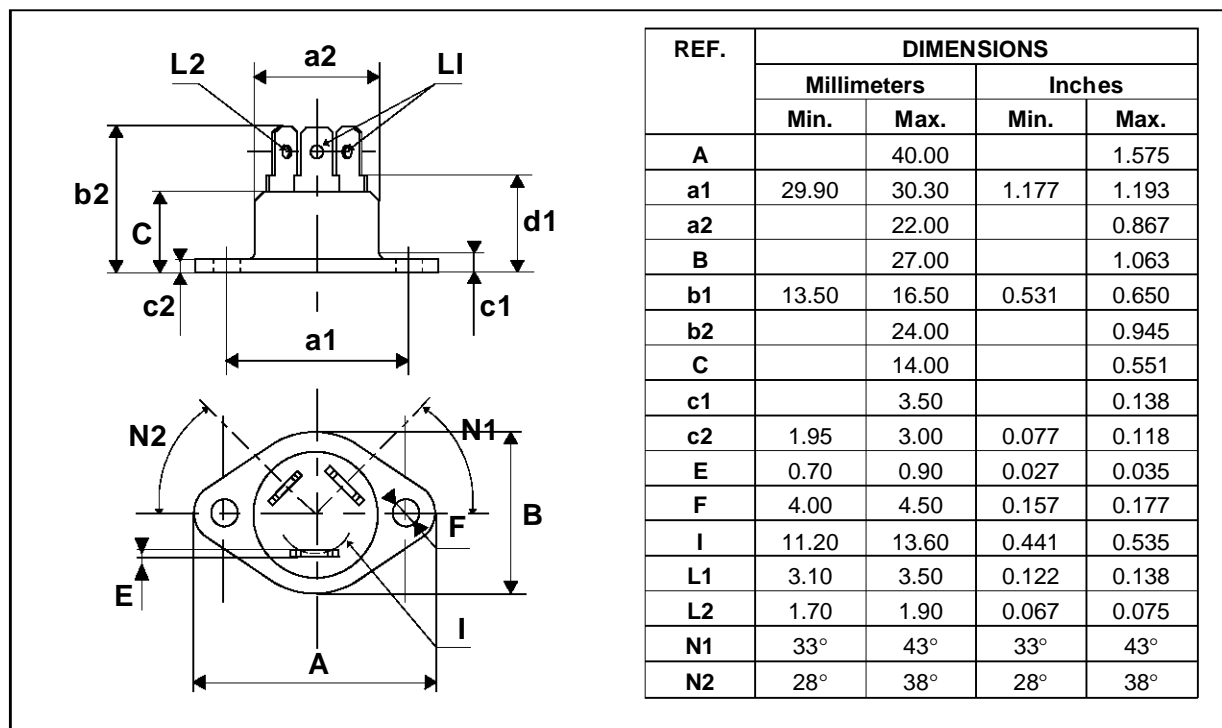


Fig.14 : On-state characteristics (maximum values) (BTW 67).



PACKAGE MECHANICAL DATA

RD 91 Plastic



Marking : type number
Weight : 20 g

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